

# International IOR Rectifier

PD - 93865A

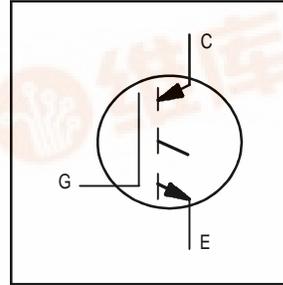
## IRGC15B120UB Die in Wafer Form

### Features

- GEN5 Non Punch Through (NPT) Technology
- UltraFast
- 10µs Short Circuit Capability
- Square RBSOA
- Positive  $V_{CE(on)}$  Temperature Coefficient

### Benefits

- Benchmark Efficiency above 20KHz
- Optimized for Welding, UPS, and Induction Heating
- Rugged with UltraFast Performance
- Excellent Current Sharing in Parallel Operation



1200V
$I_{C(nom)}=15A$
$V_{CE(on)typ.}=3.67V @$
$I_{C(nom)} @ 25^{\circ}C$
UltraFast IGBT
Short Circuit Rated
150mm Wafer

### Electrical Characteristics (Wafer Form)

Parameter	Description	Guaranteed (min, max)	Test Conditions
$V_{CE(on)}$	Collector-to-Emitter Saturation Voltage	2.85V min, 3.45V max	$I_C = 10A, T_J = 25^{\circ}C, V_{GE} = 15V$
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltage	1200V min	$T_J = 25^{\circ}C, I_{CES} = 125\mu A, V_{GE} = 0V$
$V_{GE(th)}$	Gate Threshold Voltage	4.4V min, 6.0V max	$V_{GE} = V_{CE}, T_J = 25^{\circ}C, I_C = 125\mu A$
$I_{CES}$	Zero Gate Voltage Collector Current	7µA max	$T_J = 25^{\circ}C, V_{CE} = 1200V$
$I_{GES}$	Gate-to-Emitter Leakage Current	± 1.1µA max	$T_J = 25^{\circ}C, V_{GE} = +/-20V$

### Mechanical Data

Nominal Backmetal Composition, (Thickness)	Al - Ti - Ni/V - Ag, (1kA - 1kA - 4kA - 6kA)
Nominal Front Metal Composition, (Thickness)	99% Al/1% Si, (4µm)
Dimensions	0.170" x 0.243"
Wafer Diameter	150mm, with std. < 100 > flat
Wafer Thickness, Tolerance	185µm, +/-15µm
Relevant Die Mechanical Dwg. Number	01-5381
Minimum Street Width	100µm
Reject Ink Dot Size	0.25mm diameter minimum
Ink Dot Location	Consistent throughout same wafer lot
Recommended Storage Environment	Store in original container, in dessicated nitrogen, with no contamination
Recommended Die Attach Conditions	For optimum electrical results, die attach temperature should not exceed 300°C

### Die Outline

	<p>NOTES:</p> <ol style="list-style-type: none"> <li>1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].</li> <li>2. CONTROLLING DIMENSION: [INCH].</li> <li>3. LETTER DESIGNATION: S = SOURCE      SK = SOURCE KELVIN      E = EMITTER G = GATE      IS = CURRENTSENSE</li> <li>4. DIMENSIONAL TOLERANCES: BONDING PADS:     WIDTH      &lt; 0.635 TOLERANCE = +/- 0.013     &amp;      &gt; 0.635 TOLERANCE = +/- 0.025     LENGTH      &gt; [.0250] TOLERANCE = +/- [.0010] OVERALL DIE:     WIDTH      &lt; [.050] TOLERANCE = +/- [.004]     &amp;      &gt; 1.270 TOLERANCE = +/- 0.203     LENGTH      &gt; [.050] TOLERANCE = +/- [.008]</li> </ol>
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